

# μPA1952

## DESCRIPTION

The μ PA1952 is a switching device, which can be driven directly by a 1.8 V power source.

The device features a low on-state resistance and excellent switching characteristics, and is suitable for applications such as power switch of portable machine and so on.

## FEATURES

- 1.8 V drive available
- Low on-state resistance

$R_{DS(on)1} = 135 \text{ m}\Omega \text{ MAX. (} V_{GS} = -4.5\text{V, } I_D = -1.0 \text{ A)}$

$R_{DS(on)2} = 183 \text{ m}\Omega \text{ MAX. (} V_{GS} = -2.5 \text{ V, } I_D = -1.0 \text{ A)}$

$R_{DS(on)3} = 284 \text{ m}\Omega \text{ MAX. (} V_{GS} = -1.8 \text{ V, } I_D = -0.5 \text{ A)}$

## ORDERING INFORMATION

PART NUMBER	PACKAGE
μ PA1952TE	SC-95 (Mini Mold Thin Type)

Marking: TP

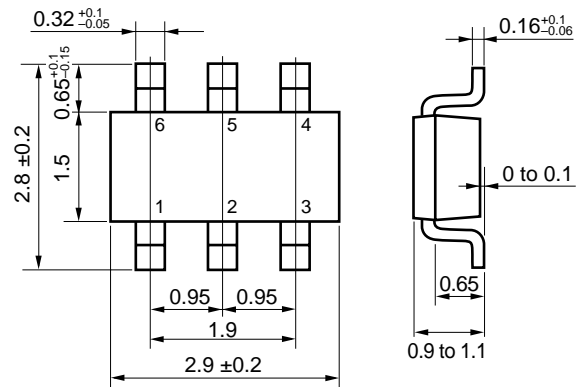
## ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C)

Drain to Source Voltage (V <sub>GS</sub> = 0 V)	V <sub>DSS</sub>	-20	V
Gate to Source Voltage (V <sub>bs</sub> = 0 V)	V <sub>GSS</sub>	±8.0	V
Drain Current (DC)	I <sub>D(DC)</sub>	±2.0	A
Drain Current (pulse) <sup>Note1</sup>	I <sub>D(pulse)</sub>	±8.0	A
Total Power Dissipation (2 units) <sup>Note2</sup>	P <sub>T1</sub>	1.15	W
Total Power Dissipation (1 unit) <sup>Note2</sup>	P <sub>T2</sub>	0.57	W
Channel Temperature	T <sub>ch</sub>	150	°C
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C

**Notes 1.** PW ≤ 10 μs, Duty Cycle ≤ 1%

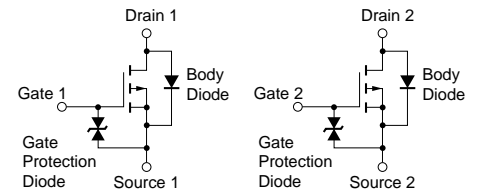
**2.** Mounted on FR-4 board of 5000 mm<sup>2</sup> x 1.1 mm, t ≤ 5 sec.

## PACKAGE DRAWING (Unit: mm)



6: Drain 1  
1: Gate 1  
5: Source 1  
4: Drain 2  
3: Gate 2  
2: Source 2

## EQUIVALENT CIRCUITS

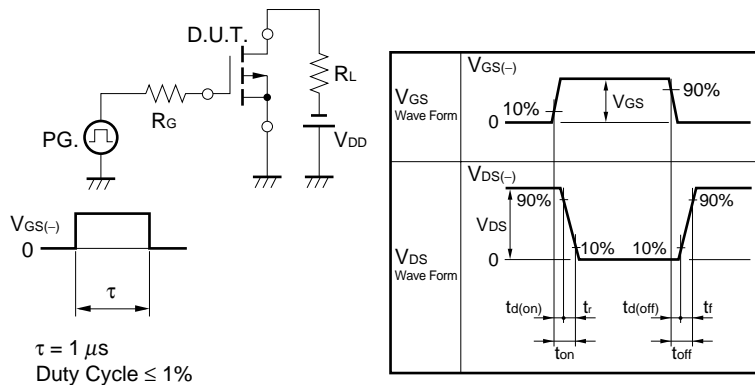


# μPA1952

## ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -20 V, V <sub>GS</sub> = 0 V			-10	μA
Gate Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±8.0 V, V <sub>DS</sub> = 0 V			±10	μA
Gate Cut-off Voltage	V <sub>GS(off)</sub>	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -1.0 mA	-0.45	-0.75	-1.5	V
Forward Transfer Admittance	y <sub>fs</sub>	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -1.0 A	1.0	4.1		S
Drain to Source On-state Resistance	R <sub>DS(on)1</sub>	V <sub>GS</sub> = -4.5 V, I <sub>D</sub> = -1.0 A		108	135	mΩ
	R <sub>DS(on)2</sub>	V <sub>GS</sub> = -2.5 V, I <sub>D</sub> = -1.0 A		137	183	mΩ
	R <sub>DS(on)3</sub>	V <sub>GS</sub> = -1.8 V, I <sub>D</sub> = -0.5 A		170	284	mΩ
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = -10 V		272		pF
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V		60		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0 MHz		30		pF
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = -10 V, I <sub>D</sub> = -1.0 A		29		ns
Rise Time	t <sub>r</sub>	V <sub>GS</sub> = -4.0 V		120		ns
Turn-off Delay Time	t <sub>d(off)</sub>	R <sub>G</sub> = 10 Ω		145		ns
Fall Time	t <sub>f</sub>			148		ns
Total Gate Charge	Q <sub>G</sub>	V <sub>DD</sub> = -16 V		2.3		nC
Gate to Source Charge	Q <sub>GS</sub>	V <sub>GS</sub> = -4.0 V		0.6		nC
Gate to Drain Charge	Q <sub>GD</sub>	I <sub>D</sub> = -2.0 A		0.6		nC
Body Diode Forward Voltage	V <sub>F(S-D)</sub>	I <sub>F</sub> = 2.0 A, V <sub>GS</sub> = 0 V		0.9		V

TEST CIRCUIT 1 SWITCHING TIME



TEST CIRCUIT 2 GATE CHARGE

